

**N-Ch MOSFET** 

# **General Description**

The WSF2060 is the highest performance trench N-ch MOSFET with extreme high cell density , which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The WSF2060 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

## **Features**

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

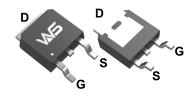
# **Product Summery**

BVDSS	RDSON	ID		
20V	3.9mΩ	60A		

# **Applications**

- High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch

## **TO-252 Pin Configuration**





# **Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	20	V
$V_{GS}$	Gate-Source Voltage	±12	V
I <sub>D</sub> @T <sub>C</sub> =25℃	Continuous Drain Current, V <sub>GS</sub> @ 10V	60	Α
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V	42	Α
I <sub>DM</sub>	Pulsed Drain Current	210	Α
EAS	Single Pulse Avalanche Energy	200	mJ
I <sub>AS</sub>	Avalanche Current	41	А
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation <sup>4</sup>	60	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	$^{\circ}$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^{\circ}$

#### **Thermal Data**

Symbol	Parameter	Тур.	Max.	Unit
R <sub>0JA</sub>	Thermal Resistance Junction-ambient (Steady State)		62	°C/W
$R_{ heta JA}$	Thermal Resistance Junction-Ambient (t ≤10s)		25	°C/W
$R_{ heta JC}$	Thermal Resistance Junction-Case		2.1	°C/W

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# Electrical Characteristics (T<sub>J</sub>=25 <sup>o</sup>C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	20			V
$\triangle BV_{DSS}/\triangle T_{J}$	BVDSS Temperature Coefficient	Reference to 25℃ , I <sub>D</sub> =1mA		0.028		V/°C
5	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =4.5V , I <sub>D</sub> =30A		3.9	5.5	mΩ
R <sub>DS(ON)</sub>		V <sub>GS</sub> =2.5V , I <sub>D</sub> =20A		5.8	8.0	
V <sub>GS(th)</sub>	Gate Threshold Voltage	V -V 1 -250A	0.5	0.75	1.0	V
$\triangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	$V_{GS}=V_{DS}$ , $I_D=250uA$		-6.16		mV/℃
	Drain-Source Leakage Current	V <sub>DS</sub> =20V , V <sub>GS</sub> =0V , T <sub>J</sub> =25℃			1	
I <sub>DSS</sub>		V <sub>DS</sub> =20V , V <sub>GS</sub> =0V , T <sub>J</sub> =55℃			5	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}$ = $\pm 20V$ , $V_{DS}$ = $0V$			±100	nA
gfs	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =30A	15			S
Rg	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		1.0	3.1	Ω
$Q_g$	Total Gate Charge (4.5V)	V <sub>DS</sub> =15V , V <sub>GS</sub> =4.5V , I <sub>D</sub> =15A		27		
Q <sub>gs</sub>	Gate-Source Charge			6.5		nC
Q <sub>gd</sub>	Gate-Drain Charge			6.4		
T <sub>d(on)</sub>	Turn-On Delay Time			6.4		
Tr	Rise Time	$V_{DD}$ =15V , $V_{GS}$ =10V , $R_{G}$ =3.3 $\Omega$		17.2		
$T_{d(off)}$	Turn-Off Delay Time			29.6		ns
T <sub>f</sub>	Fall Time			16.8		
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =15V , V <sub>GS</sub> =0V , f=1MHz		2000		
C <sub>oss</sub>	Output Capacitance			500		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			200		1

# **Diode Characteristics**

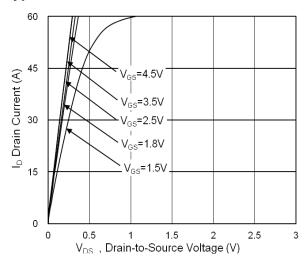
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current V <sub>G</sub>	<sub>G</sub> =V <sub>D</sub> =0V , Force Current			60	Α
V <sub>SD</sub>	Diode Forward Voltage V <sub>G</sub>	<sub>GS</sub> =0V , I <sub>S</sub> =1A , T <sub>J</sub> =25℃			1.2	V
t <sub>rr</sub>	Reverse Recovery Time			25		nS
Q <sub>rr</sub>	Reverse Recovery Charge	=20A , dl/dt=100A/µs , Tյ=25℃		24		nC

## Notes:

- **1.** Repetitive Rating: Pulse width limited by maximum junction temperature.
- **2.** Surface Mounted on FR4 Board,  $t \le 10$  sec.
- **3.** Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production
- **5.** E<sub>AS</sub> condition : Tj=25 $^{\circ}$ C,V<sub>DD</sub>=10V,V<sub>G</sub>=10V,L=0.5mH,Rg=25 $\Omega$ ,



# **Typical Characteristics**



**Fig.1 Typical Output Characteristics** 

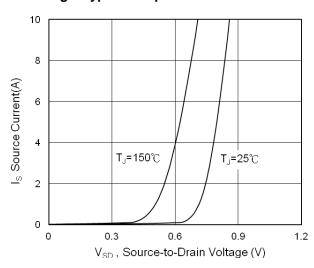


Fig.3 Forward Characteristics Of Reverse

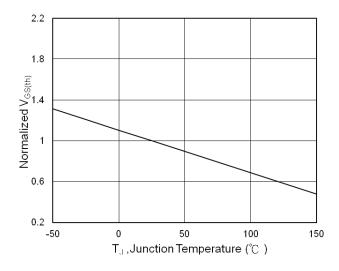


Fig.5  $V_{GS(th)}$  vs.  $T_J$ 

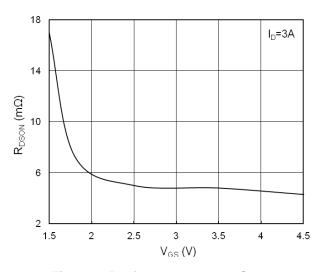
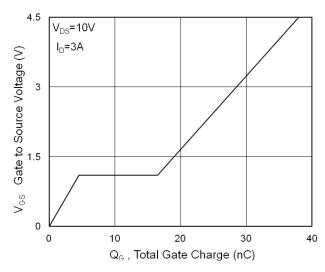


Fig.2 On-Resistance vs. Gate-Source



**Fig.4 Gate-Charge Characteristics** 

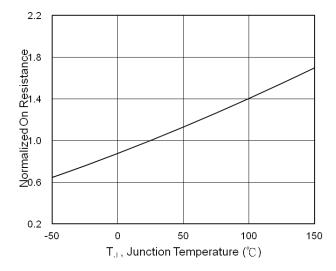
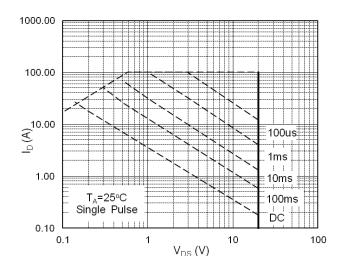


Fig.6 Normalized R<sub>DSON</sub> vs. T<sub>J</sub>





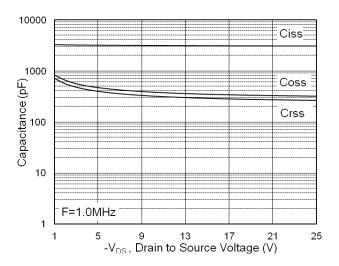


Fig.7 Capacitance

Fig.8 Safe Operating Area

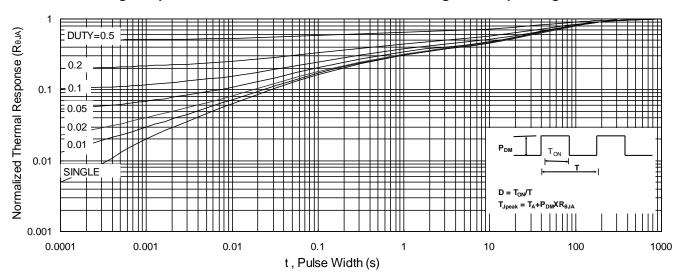


Fig.9 Normalized Maximum Transient Thermal Impedance

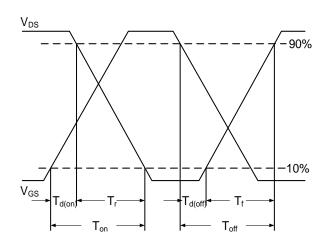


Fig.10 Switching Time Waveform

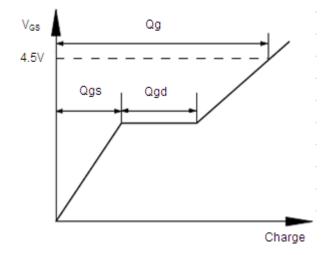


Fig.11 Gate Charge Waveform



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